

ORGANIZING INFORMATION

THE CONFERENCE IS HELD AT:

Střední škola informatiky
Čichnova 23, 624 00 BRNO-Komín

How to get there: see incl. plan by a car

From the Brno Trade Fair Exhibition Centre go in direction Brno-dam. After approx. 4 km you will see the OPEL car shop centre, on the left side. At the crossroads in front of the OPEL go to the left, at the next crossroads to the right and on the right side you will see an educational centre:

Střední škola informatiky
street Čichnova 23, BRNO-Komín

BINDING APPLICATIONS:

Will be mailed together with obligatory demand for accommodation with meals before **October 11, 2019** to the address:

SMT-INFO consortium
Údolní 53, 602 00 Brno
CZECH REPUBLIC
e-mail: info@smtinfo.cz, smtinfo@nextra.cz

Accommodation with meals:

Participants will be accommodated in the BOBY CENTRUM Brno ***

Registration:

In the conference hall
October 15, 2019 11.45 – 12.45 p.m.
October 16, 2019 8.30 – 8.45 a.m.

PROFESSIONAL GUARANTOR:

SMT-INFO, Údolní 53, 602 00 Brno
CZECH REPUBLIC

tel.: 00420-541 146 113
mobil: 00420-602 542 966
e-mail: info@smtinfo.cz, smtinfo@nextra.cz
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SMT-INFO CONSORTIUM

in cooperation with

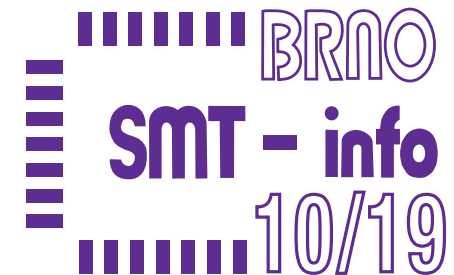
**BRNO UNIVERSITY OF TECHNOLOGY
and
SEC. SCHOOL OF INFORMATICS BRNO**

have the pleasure to invite you
to participate in the international conference

Main sponsor of dinner



Media Partner of the Conference is the Magazine
PCB ELECTRONICS A-Z



**SOLDERING AND CLEANING
PCB's IN ELECTRONICS**

**NEW TRENDS
IN MICROELECTRONICS**

SOLDER JOINT DEFECTS

BRNO, October 15–16, 2019
SŠ informatiky
Čichnova 23, Brno-Komín

event. code 10/19

CONFERENCE ORIENTATION:

- SOLDERING AND CLEANING IN ELECTRONICS
- NEW TRENDS IN MICROELECTRONICS
- TECHNIQUES IN REPAIRING
- SOLDER JOINT DEFECTS

PROFESSIONAL OFFER

- Conference participants will be acquainted with the latest information on above mentioned topics presented by specialist from prestigious companies.
- In a room adjacent the lecture theatre, the following company stands will be installed and professional literature and demonstration equipment will be offered there:

ADOPT SMT

AIM SOLDER EUROPE

AMTEST - GROUP

KOVOHUTĚ

PAN ELECTRONICS

PRAGOBOARD

ULBRICH HYDROAUTOMATIC

- Advertisement tables will be available for the conference participants and visitors, providing propagation of their own products and offer of non-used/used technological equipment and services.

THEMATIC ORIENTATION OF OTHER EVENTS

ORGANIZED BY SMT-INFO:

SMT-INFO 02/20 Brno, 11th February, 2020

Technical and Business Seminar

- PCB DESIGN SYSTEMS
- PCB PRODUCTION AND DEFECTS
- COMPLEX PRODUCTION LINES FOR MODERN ASSEMBLY
- INSPECTION SYSTEMS

PROFESSIONAL GUARANTOR:

SMT-INFO CONSORTIUM, Údolní 53, 602 00 Brno

e-mail: info@smtinfo.cz, smtinfo@nexta.cz

mobil: 00420-602 542 966

CONFERENCE SCHEDULE

Tuesday, October 15, 2019

- 12.20 - Lunch
- 12.50 - Opening, Introduction
- 13.00 - Soldering – Surface Tension Phenomenon
/K. Dušek, FEL ČVUT Praha/
- 13.20 - A Case Study Comparing AIM Novel Lead Free Alloys to Other Low/No Silver Alloys
/A. Sedlák, AIM SOLDER EUROPE/
- 13.40 - Void Reduction Programme in Solder Joints
/C. Hoppenbrouwers, ALPHA ASSEMBLY SOLUTIONS, M Cichra, ERMEG Liberec/
- 14.40 - Break – Coffee, Refreshment
- 15.00 - HDI Production, Rigid-Flex and Special PCBs-Materials and Technology
/O. Šimek, PRAGOBOARD Praha/
- 15.40 - Novo, Cerno, Integra – Selective soldering with Nordson SELECT
/F. Sommer, NORDSON SELECT, L. Pokorný, AMTEST GROUP Brno/
- 16.20 - Discussion
- 16.30 - Humiseal – Materials for Coating, Potting, Adhesives and Thermal Management /B. Gyorffy, HUMISEAL, J. Vondráček, AMTEST GROUP Brno/
- 17.00 - Smart Sensors in Modern Soldering Machines
/M. Hurban, REHM Česká republika Příbor/
- 17.20 - Manual Solder Paste Dispenser with Very Low Production Cost
/K. Dušek, FEL ČVUT Praha/
- 17.30 - The First Day Conference Closing with Continuing of Friendly Discussion with Dinner and Refreshment

AMTEST GROUP
and SMT-info consortium Invitation
for Dinner

Wednesday, October 16, 2019

- 8.45 - Opening the Second Day of Conference
- 8.50 - Soldering Results – Effect of Solder Bath Contamination
/P. Gábriš, INTEGRATED MICRO-ELECTRONICS Třemošná/
- 9.10 - FUJI Corporation, Company Profile and Future Strategies
/J. Ernst, FUJI, N. Hrbek, AMTECH Brno/
- 9.50 - Why Cleaning PCB – Methods and Chemistry of Cleaning /M. Šaffer, PBT Rožnov p. R./
- 10.10 - Selective Laser Soldering – Clean No Contact Process
/R. Gajdůšek, PBT Rožnov p. Radh./
- 10.30 - Break – Coffee, Refreshment
- 10.50 - AXI – strong support for modern productions
 - Can automatic in-line X-ray help in demanding electronic production?
 - Is AXI comparable with AOI?
/M. Drlík, IMT Technologies & Solution Valašské Meziříčí/
- 11.30 - Mechanism of Defects in Electronics – Tin Whiskers (IEC 60068-2-82, IEC/TS 62647, csWikipedia, enWikipedia)
/K. Jurák, Praha, Z. Nejezchlebová, Agentura ČAS Praha/
- 11.50 - Discussion
- 12.00 - Advantages of Laser Soldering in Electronics
/P. Lacko, QUIPTECH Brno/
- 12.30 - Latest in PCB Protection
/R. Píkrýl, ULBRICH HYDROAUTOMATIC Brno/
- 12.50 - How to fulfil Reliability Requirements for Modern Electronic Assemblies
/V. Sítko, PBT WORKS Rožnov p. R./
- 13.30 - Discussion, Closing the Second Day of Conference - Lunch

Lectures in English and German will be interpreted.
Program changes reserved.